

# EVVOSEMI<sup>®</sup>

THINK CHANGE DO



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

|              |             |         |
|--------------|-------------|---------|
| ▶ Domestic   | Part Number | IRF7311 |
| ▶ Overseas   | Part Number | IRF7311 |
| ▶ Equivalent | Part Number | IRF7311 |

EV is the abbreviation of name EVVO

## 30V 2N-Channel Enhancement Mode MOSFET

### General Description

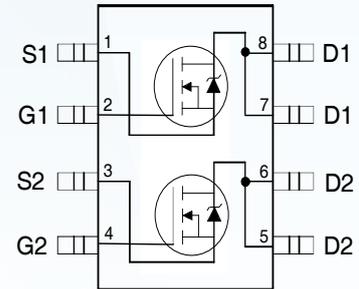
The IRF7311 is the highest performance trench 2N-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the small power switching and load switch applications. They meet the RoHS and Product requirement with full function reliability approved.

### General Features

V<sub>DS</sub> = 30V I<sub>D</sub> = 9A

R<sub>DS(ON)</sub> < 13mΩ @ V<sub>GS</sub>=10 V

R<sub>DS(ON)</sub> < 18mΩ @ V<sub>GS</sub>=4.5V



SOP-8

### Application

Battery protection

Load switch

Uninterruptible power supply

### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

| Symbol                                | Parameter  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| V <sub>DS</sub>                       | Drain-Source Voltage   | 30         | V     |
| V <sub>GS</sub>                       | Gate-Source Voltage  | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 9          | A     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 8.2        | A     |
| I <sub>D</sub> @T <sub>A</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 6.5        | A     |
| I <sub>D</sub> @T <sub>A</sub> =70°C  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 5.6        | A     |
| I <sub>DM</sub>                       | Pulsed Drain Current <sup>2</sup>                            | 30         | A     |
| EAS                                   | Single Pulse Avalanche Energy <sup>3</sup>                   | 15         | mJ    |
| I <sub>AS</sub>                       | Avalanche Current  | 22         | A     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>                         | 1.6        | W     |
| P <sub>D</sub> @T <sub>A</sub> =70°C  | Total Power Dissipation <sup>4</sup>                         | 1.0        | W     |
| T <sub>STG</sub>                      | Storage Temperature Range                                    | -55 to 150 | °C    |
| T <sub>J</sub>                        | Operating Junction Temperature Range                         | -55 to 150 | °C    |
| R <sub>θJA</sub>                      | Thermal Resistance Junction-Ambient <sup>1</sup>             | 75         | °C/W  |
| R <sub>θJC</sub>                      | Thermal Resistance Junction-Case <sup>1</sup>                | 4.8        | °C/W  |

## 30V 2N-Channel Enhancement Mode MOSFET

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol                              | Parameter                                      | Conditions   | Min. | Typ.  | Max.     | Unit  |
|-------------------------------------|--|--|------|-------|----------|-------|
| BV <sub>DSS</sub>                   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA   | 30   |       |          | V     |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | BVDSS Temperature Coefficient                  | Reference to 25 °C, I <sub>D</sub> =1mA  |      | 0.023 |          | V/°C  |
| R <sub>DS(ON)</sub>                 | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =15A<br>V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A  |      |       | 13<br>18 | mΩ    |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA   | 1.0  |       | 2.5      | V     |
| ΔV <sub>GS(th)</sub>                | V <sub>GS(th)</sub> Temperature Coefficient    |  |      | -5.08 |          | mV/°C |
| I <sub>DSS</sub>                    | Drain-Source Leakage Current                   | V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C<br>V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C |      |       | 1<br>5   | uA    |
| I <sub>GSS</sub>                    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   |      |       | ±100     | nA    |
| g <sub>fs</sub>                     | Forward Transconductance                       | V <sub>DS</sub> =5V, I <sub>D</sub> =15A   |      | 32    |          | S     |
| R <sub>g</sub>                      | Gate Resistance                                | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz   |      | 1.7   |          | Ω     |
| Q <sub>g</sub>                      | Total Gate Charge (4.5V)                       |  |      | 5.3   |          | nC    |
| Q <sub>gs</sub>                     | Gate-Source Charge                             | V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A   |      | 0.78  |          |       |
| Q <sub>gd</sub>                     | Gate-Drain Charge                              |  |      | 2.2   |          |       |
| T <sub>d(on)</sub>                  | Turn-On Delay Time                             | V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =1.5Ω<br>I <sub>D</sub> =20A  |      | 6.4   |          | ns    |
| T <sub>r</sub>                      | Rise Time                                      |  |      | 39    |          |       |
| T <sub>d(off)</sub>                 | Turn-Off Delay Time                            |  |      | 21    |          |       |
| T <sub>f</sub>                      | Fall Time                                      |  |      | 4.7   |          |       |
| C <sub>iss</sub>                    | Input Capacitance                              | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz  |      | 580   |          | pF    |
| C <sub>oss</sub>                    | Output Capacitance                             |  |      | 97    |          |       |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                   |  |      | 39    |          |       |
| I <sub>S</sub>                      | Continuous Source Current <sup>1,5</sup>       | V <sub>GS</sub> =V <sub>D</sub> =0V, Force Current   |      |       | 37       | A     |
| I <sub>SM</sub>                     | Pulsed Source Current <sup>2,5</sup>           |  |      |       | 75       | A     |
| V <sub>SD</sub>                     | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C  |      |       | 1        | V     |

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=22A
4. The power dissipation is limited by 175°C junction temperature
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

30V 2N-Channel Enhancement Mode MOSFET

Typical Characteristics

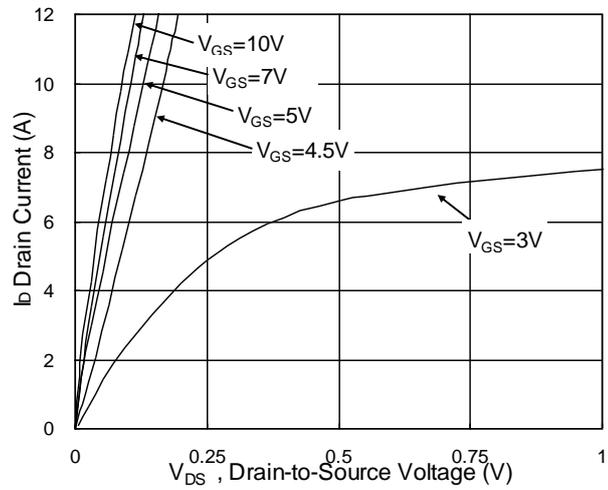


Fig.1 Typical Output Characteristics

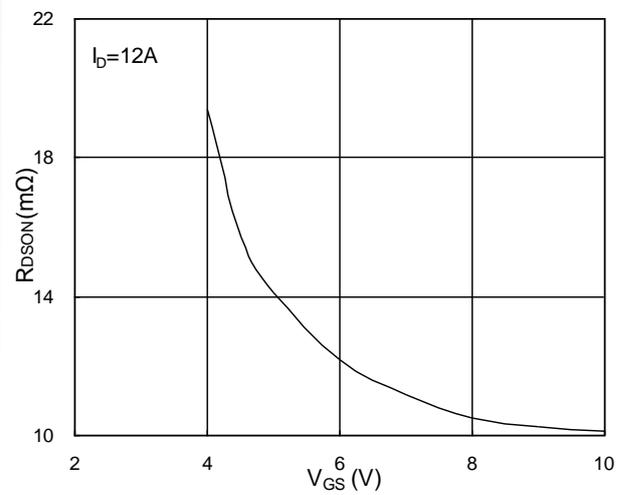


Fig.2 On-Resistance vs. G-S Voltage

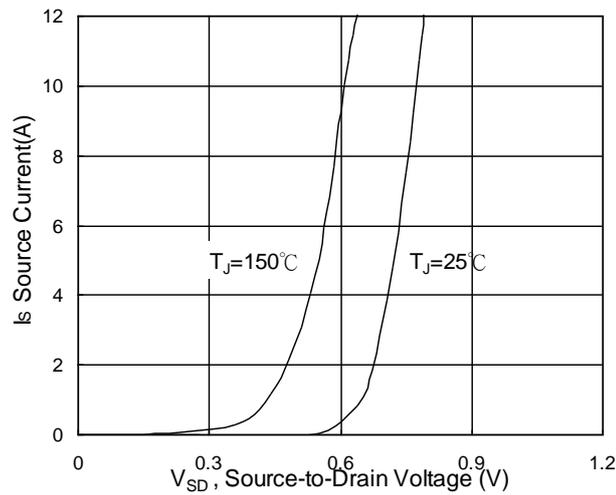


Fig.3 Forward Characteristics of Reverse

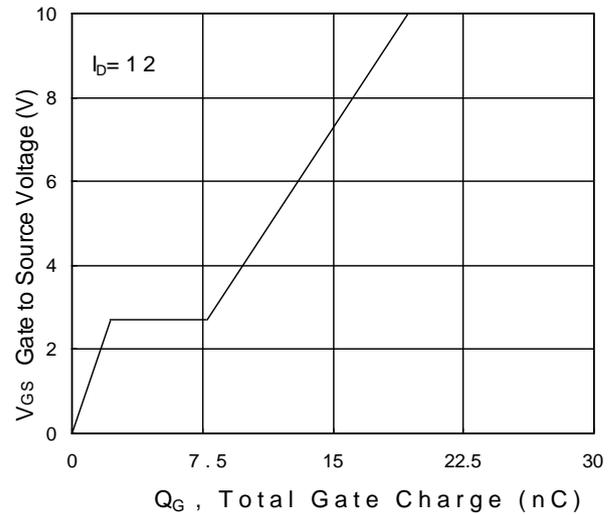


Fig.4 Gate-charge Characteristics

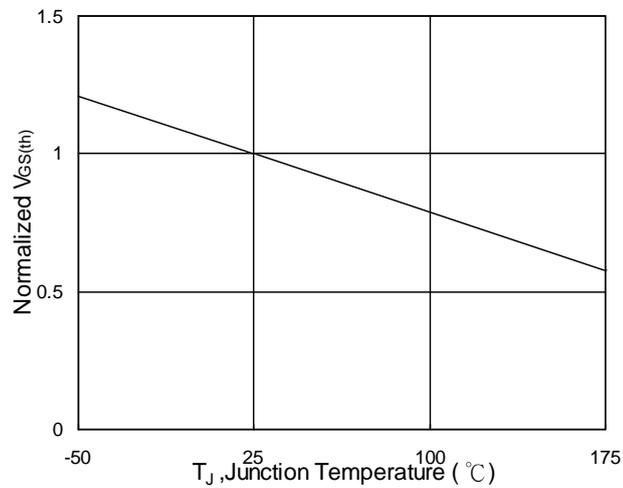


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

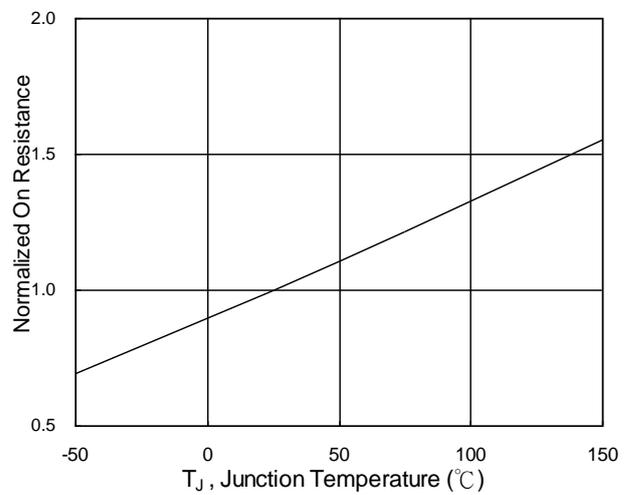


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

30V 2N-Channel Enhancement Mode MOSFET

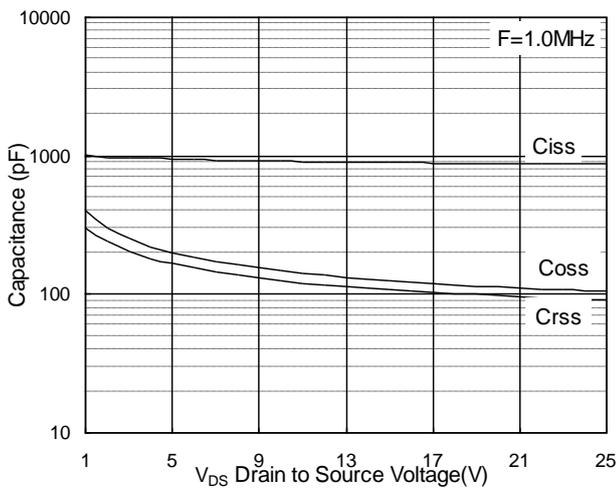


Fig.7 Capacitance

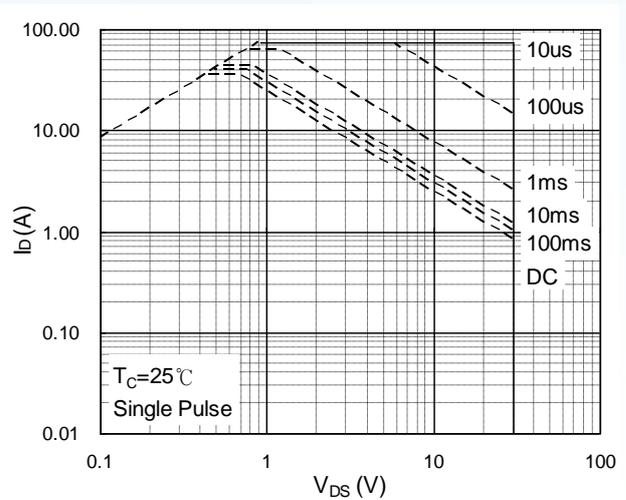


Fig.8 Safe Operating Area

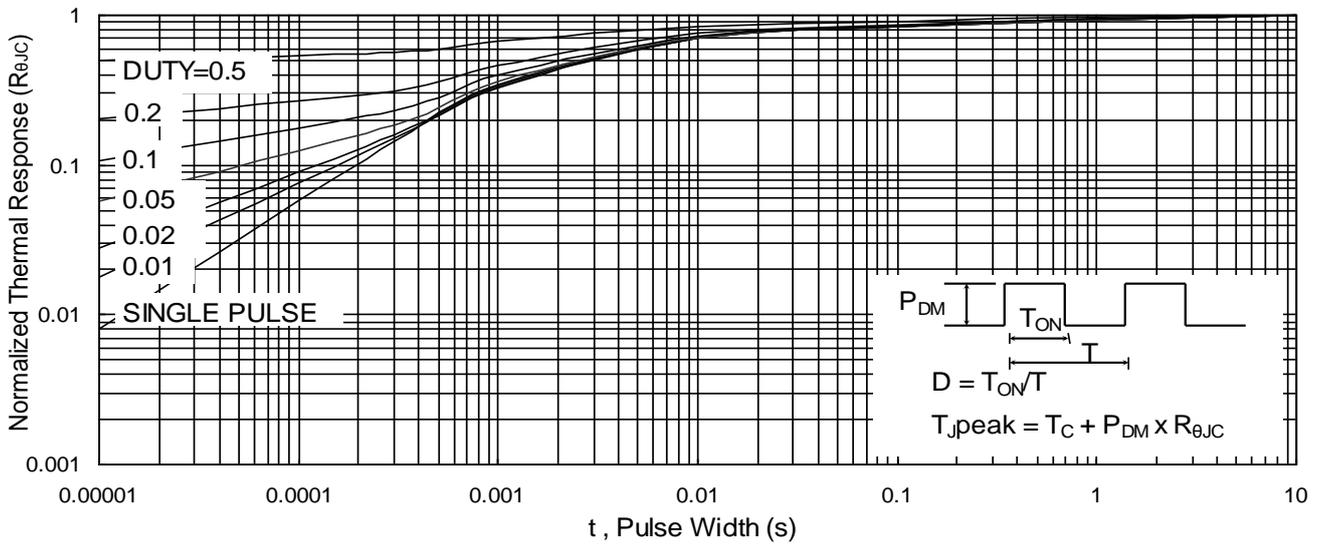


Fig.9 Normalized Maximum Transient Thermal Impedance

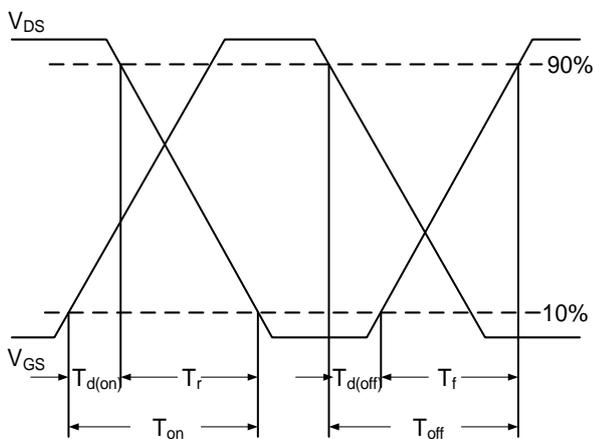


Fig.10 Switching Time Waveform

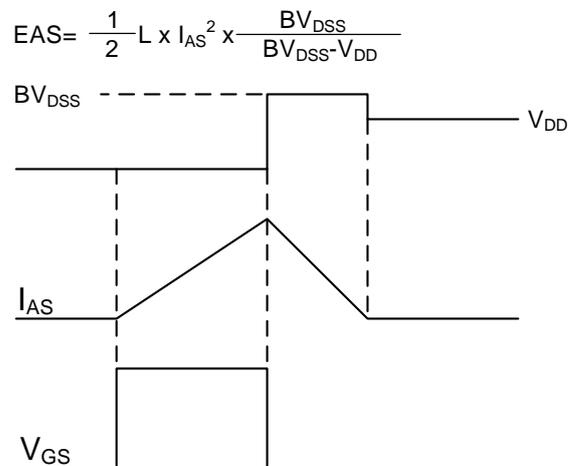
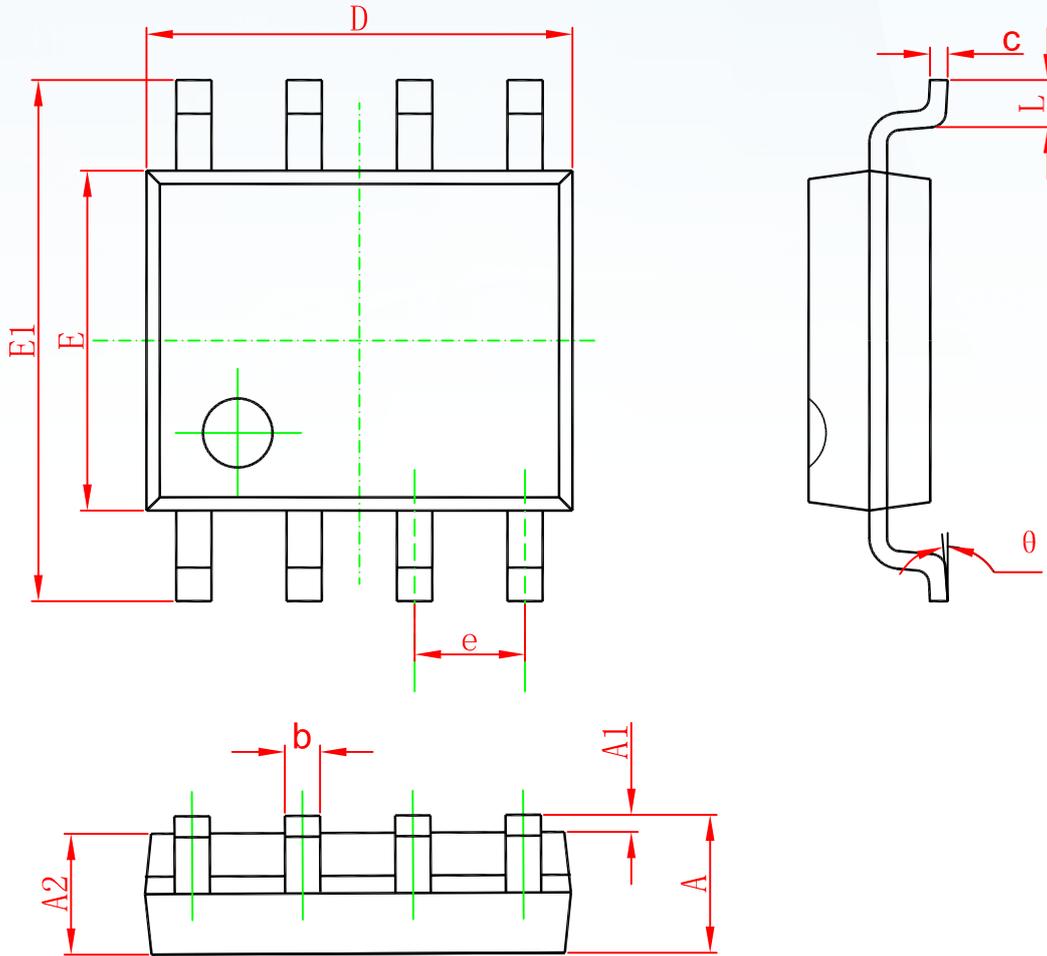


Fig.11 Unclamped Inductive Waveform

**30V 2N-Channel Enhancement Mode MOSFET**

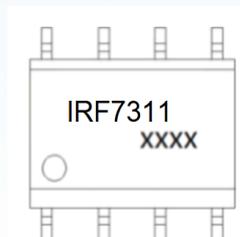
**SOP-8**



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270(BSC)                |       | 0.050(BSC)           |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |

## 30V 2N-Channel Enhancement Mode MOSFET

## Marking



## Ordering information

| Order code | Package | Baseqty | Deliverymode  |
|------------|---------|---------|---------------|
| IRF7311    | SOP-8   | 3000    | Tape and reel |

## Disclaimer

EVVOSEMI ("EVVO") reserves the right to make corrections, enhancements, improvements, and other changes to its products and services at any time, and to discontinue any product or service without notice.

EVVO warrants the performance of its hardware products to the specifications applicable at the time of sale in accordance with its standard warranty. Testing and other quality control techniques are used as deemed necessary by EVVO to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

Customers should obtain and confirm the latest product information and specifications before final design, purchase, or use. EVVO makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does EVVO assume any liability for application assistance or customer product design. EVVO does not warrant or accept any liability for products that are purchased or used for any unintended or unauthorized application.

EVVO products are not authorized for use as critical components in life support devices or systems without the express written approval of EVVOSEMI.

The EVVO logo and EVVOSEMI are trademarks of EVVOSEMI or its subsidiaries in relevant jurisdictions. EVVO reserves the right to make changes without further notice to any products herein.